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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No. 10/618,471
Confirmation No. 5311
Filing Date July 11, 2003
Inventor Luan C. Tran
Assignee Micron Technology, Inc.
Group Art Unit 2813
Examiner Laura M. Schillinger
Customer No. 021567
Attorney Docket No. MI22-2331
Title: Semiconductor Processing Methods of Forming Integrated Circuitry

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT


References -- See Attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

Citation of these references is respectfully requested.

Respectfully submitted,

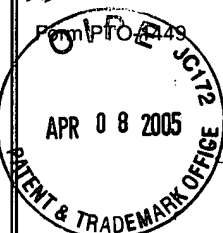
Dated: April 8, 2005

By: 
Deepak Malhotra
Reg. No. 33,560

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		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-2331		SERIAL NO. 10/618,471	
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					
		APPLICANT: Luan C. Tran				FILING DATE July 11, 2003	

U.S. PATENT DOCUMENTS							
*Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	5,252,504	10/1993	LOWREY ET AL.	437	34	
	AB	6,545,904	04/2003	TRAN	365	149	
	AC	6,803,278	10/2004	TRAN	438	258	
	AD	6,759,288	07/2004	TRAN ET AL.	438	194	
	AE	6,358,787	03/2002	DENNISON ET AL	438	231	
	AF						
	AG						
	AH						
	AI						
	AJ						

FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AJ							
	AK							
	AL							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)			
	AM		
	AN		
	AO		

EXAMINER	DATE CONSIDERED
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.